EAST Search History

Ref#	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
_1	5025	382/149,145,224,159,100,141,155,181.OCLS.	USPAT	OR	ON	2009/06/29 11:58
2	4478	715/774,835,837,764,841,210,839,762,809,804,973,250,866,708.CCLS.	USPAT	OR	ON	2009/06/29 12:01
.3	1453	719/310,315.CQLS.	USPAT	OR	ON	2009/06/29 12:01
.4	355	714/E11.21.00LS.	USPAT	OR	ON	2009/06/29 12:02
.5	1846	356/237.1,237.2.OOLS.	USPAT	OR	ON	2009/06/29 12:03
.6	834	702/35,1,33.OCLS.	USPAT	OR	ON	2009/06/29 12:04
.7	599018	(waler\$1 or semicondudor\$1 or chip\$1 or subtrat\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:29
8	125	L7 and user adj select\$3 and review and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:32
9	3	L8 and input adj user and page and learning adj mode and parameters	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:34
.10	4	L8 and input and user and page and learning adj mode and parameters	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:37
.11	4	L8 and learning adj mode and parameters	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:55

.12	1	il.8 and automatic adj defect and recognition and(detect\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3)and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:58
.13	11	automatic adj defect and recognition and/deted\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3)and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:59
.14	10	L13 and(wafer\$1 or semicondudor\$1 or chip\$1 or subtrat\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 12:59
.15	1	L14 and user adj select\$3 and review and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 13:00
16	1	1.14 and user adj select\$3 and review adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 13:00
17	3	automatic adj defect and recognition and(detect\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)and select\$3 adj(wafer\$1 or semicondudor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or cod or camera)and (illumination or source or light or optimal adj intensity or light adj intensity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 13:12
.18	3	automatic adj defect and recognition and(detect\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)and select\$3 adj(wafer\$1 or semicondudor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or cod or camera)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 13:16
.19	0	(L18 and(@ad<"20030712" or @rlad<"20030712" or @prad<"20030712" or @prad<"20030712" or @prad<"20030712")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 13:17
21	781	L1 and(wafer\$1 or semicondudor\$1 or chip\$1 or subtrat\$1)	USPAT	OR	ON	2009/06/29 13:19
22	3	L21 and user adj select\$3 and review and data adj file	USPAT	OR	ON	2009/06/29 13:19

23	27	1.21 and user adj select\$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 13:20
24	0	1.23 and input and user and page and learning adj mode and parameters	USPAT	OR	ON	2009/06/29 13:21
26	0	123 and automatic adj defect and recognition and(detect\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)and select\$3 adj(wafer\$1 or semicondudor\$i or chip\$i or substrat\$1)and(capturing or pictures or cod or camera)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 13:23
27	0	i.23 and automatic adj defect and recognition and/detect\$3 or determining)and(defect or flaw or fault) and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)and select\$3 adj(wafer\$1 or semicondudor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or cod or camera)and (illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 13:24
28	2	1.23 and automatic adj defect and recognition and(detect\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)	USPAT	OR	ON	2009/06/29 13:25
29	2	L28 and (@ad<"20030712" or @rlad<"20030712" or @prad<"20030712" or @prad<"20030712" or @plad<"20030712" or	USPAT	OR	ON	2009/06/29 13:28
30	0	fi.28 and select\$3 adj(wafer\$1 or semicondudor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or cod or camera)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 13:32
31	0	[1.28 and select\$3 adj(wafer\$1 or semicondudor\$1 or chip\$1 or substrat\$1) and(capturing or pictures or cod or camera) and (illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 13:43
32	0	it.28 and select\$3 adj(wafer\$1 or semicondudor\$1 or chip\$1 or substrat\$1) and(capturing or pictures or ccd or camera) and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast) and(detect\$3 or determining) and(defect or flaw or fault)	USPAT	OR	ON	2009/06/29 13:46
33	18	12 and(wafer\$1 or semicondudor\$1 or chip\$1 or subtrat\$1)	USPAT	OR	ON	2009/06/29 13:48
34	4	L33 and user adj select\$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 13:48
35	0	L34 and automatic adj defect and recognition and(detect\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)	USPAT	OR	ON	2009/06/29 13:48
36	0	il.34 and select\$3 adj(wafer\$1 or semicondudor\$1 or chip\$1 or substrat\$1)and(capturing or pictures or ccd or camera)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 13:52
37	2	L3 and(wafer\$1 or semicondudor\$1 or chip\$1 or subtrat\$1)	USPAT	OR	ON	2009/06/29 13:53
38	0	1.37 and automatic adj defect and recognition and(detect\$3 or determining) and(defect or flauk or fault) and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)	USPAT	OR	ON	2009/06/29 13:55

.39	0	L37 and user adj select\$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 13:56
40	0	L37 and select\$3 adj{wafer\$1 or semicondudor\$1 or chip\$1 or substrat\$1) and(capturing or pictures or cod or camera) and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 13:56
41	2	L3 and(wafer\$1 or semicondudor\$1 or chip\$1 or subtrat\$1)	USPAT	OR	ON	2009/06/29 13:59
42	1	L4 and(waler\$1 or semicondudor\$1 or chip\$1 or subtrat\$1)	USPAT	OR	ON	2009/06/29 13:59
43	0	L42 and automatic adj defect and recognition and(detect\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)	USPAT	OR	ON	2009/06/29 13:59
44	0	L42 and user adj select\$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 13:59
45	0	L42 and select\$3 adj[(wafer\$1 or semicondudor\$1 or chip\$1 or substrat\$1) and(capturing or pictures or cod or camera)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 14:00
46	733	L5 and(wafer\$1 or semicondudor\$1 or chip\$1 or subtrat\$1)	USPAT	OR	ON	2009/06/29 14:01
47	5	L46 and automatic adj defect and recognition and(detect\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)	USPAT	OR	ON	2009/06/29 14:01
48	0	L47 and user adj select\$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 14:01
49	0	L47 and select\$3 adj[(wafer\$1 or semicondudor\$1 or chip\$1 or substrat\$1) and(capturing or pictures or cod or camera)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 14:01
50	5	L47 and (@ad<"20030712" or @rlad<"20030712" or @prad<"20030712" or @prad<"20030712" or @prad<"20030712")	USPAT	OR	ON	2009/06/29 14:02
51	0	L47 and user adj select\$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 14:03
52	599018	(waler\$1 or semicondudor\$1 or chip\$1 or subtrat\$1)	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 14:04
53	83	defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 14:04

.54	19	L53 and (wafer\$1 or semicondudor\$1 or chip\$1 or subtral\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 14:04
55	12	L54 and @ad< "20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 14:04
56	3	L55 and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 14:04
57	685554	L56 and select\$3 and review and data file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 14:04
58	18	L53 and select\$3 and review and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 14:04
59	17	L58 and parameters	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 14:04
60	2	L52 and L53 and L57 and L59	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 14:04
.61	0	L60 and @ad<"20030712"	USPAT	OR	ON	2009/06/29 14:04
63	129	L6 and(wafer\$1 or semicondudor\$1 or chip\$1 or subtrat\$1)	USPAT	OR	ON	2009/06/29 14:06
64	4	L63 and user adj select\$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 14:06
.65	0	L64 and select\$3 adj(wafer\$1 or semicondudor\$1 or chip\$1 or substrat\$1) and(capturing or pictures or cod or camera) and align\$4 and(illumination or source or light or optimal adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 14:07

.66	0	L64 and automatic adj defect and recognition and(defect\$3 or defermining) and(defect or flaw or fault) and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)	USPAT	OR	ON	2009/06/29 14:08
67	3	L64 and(@ad<"20030712" or @rlad<"20030712" or @prad<"20030712" or @prad<"20030712" or @prad<"20030712" or	USPAT	OR	ON	2009/06/29 14:09
58	0	L67 and select\$3 adj(wafer\$1 or semicondudor\$1 or chip\$1 or substrat\$1) and(capturing or pictures or cod or camera) and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 14:23
59	1	L63 and automatic adj defect and recognition and(detect\$3 or determining) and(defect or flaw or fault) and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)	USPAT	OR	ON	2009/06/29 14:26
70	0	L69 and select\$3 adj(wafer\$1 or semicondudor\$1 or chip\$1 or substrat\$1) and(capturing or pictures or cod or camera) and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 14:26
71	0	L69 and user adj select\$3 and review and(storage or stored or memory or data adj file)	USPAT	OR	ON	2009/06/29 14:28
79	1	((wafer\$1 or semicondudor\$1 or chip\$1 or subtrat\$1) and user adj select\$3 and review and data adj file and input and user and page and learning adj mode).clm.	US-PGPUB	OR	ON	2009/06/29 14:51
31	1	L69 and automatic adj defect and recognition and(detect\$3 or determining)and(defect or flaw or fault) and(assign\$3 or test\$3 or evaluat\$3 or accept\$3)	USPAT	OR	ON	2009/06/29 14:55
32	0	L81 and select\$3 adj[wafer\$1 or semicondudor\$1 or chip\$1 or substrat\$1) and(capturing or pictures or cod or camera) and(detect\$3 or determining) and(defect or flaw or fault) and (assign\$3 or test\$3 or evaluat\$3) and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	US-PGPUB; USPAT; EPO; JPO; DERWENT; BM_TDB	OR	ON	2009/06/29 14:59
33	0	LB1 and select\$3 adj[wafer\$1 or semicondudor\$] or chip\$l or substrat\$1) and(capturing or pictures or cod or camera) and(detect\$3 or determining) and(defect or flaw or fault) and (assign\$3 or test\$3 or evaluat\$3) and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	USPAT	OR	ON	2009/06/29 14:59
34	0	accept\$3 adj select\$3 adj (wafer\$1 or semicondudor\$1 or chip\$1 or substrat\$1) and(capturing or pictures or ccd or camera)and(detect\$3 or determining)and(defect or flaw or fault)and (assign\$3 or test\$3 or evaluat\$3)and align\$4 and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 15:14
35	0	accept(\$3 adj select(\$3 adj (wafer(\$1 or semicondudor(\$1 or chip(\$1 or substrat(\$1) and(capturing or pictures or cod or camera)and(detect(\$3 or determining)and(defect or flaw or fault)and (assign(\$3 or test(\$3) or evaluat(\$3))and(illumination or source or light or optimal adj intensity or light adj intensity or brightness or contrast)	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2009/06/29 15:15
1	571947	(wafer\$1 or semicondudor\$1 or chip\$1 or subtrat\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:27

32	1	St and automatic and defect adj classification and teaching and knowledge adj based adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:29
3	1	automatic and defect adj classification and teaching and knowledge adj based adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:30
¥	1	St and defect adj classification and teaching and knowledge adj based adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:30
35	1	defect adj classification and teaching and knowledge adj based adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:30
6	2	defect adj classification and knowledge adj based adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:31
57	82	defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:31
38	19	S7 and (wafer\$1 or semicondudor\$1 or chip\$1 or subtrat\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:31
39	17	Ss and(@ad<"20030712" or @riad<"20030712" or @prad<"20030712" or @prad<"20030712" or @prad<"20030712")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:36
310	12	\$3 and @ad< "20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/12/05 11:36

311	24	((DIRK) near2 (SOENKSEN)).INV.	US-PGPUB; USPAT	OR	ON	2008/12/05 11:36
12	11	((PALF) near2 (FRIEDRICH)).INV.	US-PGPUB; USPAT	OR	ON	2008/12/05 11:37
13	1	((ANDREAS) near2 (DRAEGER)).INV.	US-PGPUB; USPAT	OR	ON	2008/12/05 11:37
14	2	((DETLEF) near2 (SOHUPP)).INV.	US-PGPUB; USPAT	OR	ON	2008/12/05 11:37
16	2	((THIN) near2 ("VAN LUU")).INV.	US-PGPUB; USPAT	OR	ON	2008/12/05 11:39
17	3	((WOLFGANG) near2 (LANGER)).INV.	US-PGPUB; USPAT	OR	ON	2008/12/05 11:39
18	0	S11 and defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:40
19	0	S11 and defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:40
20	0	S11 and defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:41
21	0	S12 and defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:41
22	0	S13 and defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:43
23	3	S10 and descriptor	US-PGPUB; USPAT; EPO; JPO; DEFWENT; IBM_TDB	OR	ON	2008/12/05 11:46

S24	638382	\$23 and select\$3 and review and data file	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:47
\$25	0	\$23 and select\$3 and review and data adj file	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:47
S26	18	S7 and select\$3 and review and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:48
27	0	S26 and parameters and learning adj node	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:49
228	0	S26 and parameters and learning adj mode	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:49
229	17	\$26 and parameters	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:49
330	2	S1 and S7 and S24 and S29	US PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:56
331	2	\$30 and @ad<"20030712"	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 11:56
S32	18	S7 and S26	(US-PGPUB; USPAT; EPO; JPO; DERWENT; (BM_TDB	OR	ON	2008/12/05 11:57

533	16	S32 and @ad<"20030712"	US-PGPUB; USPAT; EPO; UPO; DERWENT; BM_TDB	OR	ON	2008/12/05 11:58
334	20	St and automatic and defect adj recognition	US-PGPUB; USPAT; EPO; UPO; DERWENT; BM_TDB	OR	ON	2008/12/05 12:00
335	638382	S34 and select\$3 and review and data file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:01
336	4	S34 and descriptor	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:33
337	1	S34 and learning adj mode	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:34
338	0	S37 and @ad<"20030712"	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:34
339	16	S34 and @ad<"20030712"	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:35
340 341	0	S39 and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:35
341	2	S39 and learning	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:35

S42	16	\$26 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; JBM_TDB	OR	ON	2008/12/05 12:39
343	0	S42 and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:40
344	0	S42 and learning near mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:40
345	0	S42 and learning near3 mode	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:40
346	11	S42 and descriptor	US-PGPUB; USPAT; EPO; UPO; DERWENT; I BM_TDB	OR	ON	2008/12/05 12:40
347	598	St and select\$3 and review and data adj file	US-PGPUB; USPAT; EPO; UPO; DERWENT; I BM_TDB	OR	ON	2008/12/05 12:44
548	340	S47 and @ad<"20030712"	US-PGPUB; USPAT; EPO; UPO; DERWENT; I BM_TDB	OR	ON	2008/12/05 12:44
549	1	S48 and input and user and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; I BM_TDB	OR	ON	2008/12/05 12:45
350	1	S48 and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:46

351	4	S48 and alignment adj procedure	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 12:46
352	0	S3 and automatic adj defect and recognition and(detect\$3 or determining)same (defect or flaw or fault)same(assign\$3 or test\$3 or evaluat\$3)same descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:02
353	0	\$48 and automatic adj defect and recognition and(detect\$3 or determining)same (defect or flaw or fault)same(assign\$3 or test\$3 or evaluat\$3)same descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; BM_TDB	OR	ON	2008/12/05 13:02
354	1	automatic adj defect and recognition and(detect\$3 or determining)same (defect or flaw or fault)same(assign\$3 or test\$3 or evaluat\$3)same descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:02
355	11	automatic adj defect and recognition and(detect\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3)and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:03
356	5	S55 and @ad< '20030712'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:03
357	1	S56 and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:03
358	0	S57 and edit adj recipe	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:05
359	0	S57 and edit	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:05

S60 S61	0	S57 and memory adj circuits	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:07
361	1	S57 and circuits	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:07
362	0	961 and logic adj circuits	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:08
363	0	\$61 and blank adj wafer\$1	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 13:08
364	1	S56 and learning adj mode	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/05 14:02
365	571947	(waler\$1 or semicondudor\$1 or chip\$1 or subtrat\$1)	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:12
366	2	S65 and select\$3 and review adj data adj file	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:13
367	2	S65 and review adj data adj file	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:13
368	638	S65 and review and data adj file	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:14

S69	134	S65 and review same data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:14
 370	0	Ss9 and defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:15
371	0	S69 and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:15
572	1	959 and classification and knowledge near3 database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:15
373	11	S58 and classification and knowledge near3 database	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:15
374	5	\$73 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:16
375	5	S74 and review and data adj file	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:16
376	1	S75 and (user or operator or human)and page and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:17
377	1	S75 and (user or operator or human)and learning adj mode	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:17

S78	9	\$58 and(detect\$3 or determining) and (defect or fault or flaw)and classification and knowledge near3 database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:19
379	13	learning and(knowledge-based or knowledge adj based)and database and automatic and defect adj classification	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:21
380	10	S79 and @ad< "20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:21
381	0	590 and review and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:21
82	1	S80 and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:22
83	8	\$80 and(wafer\$1 or semicondudor\$1 or chip\$1 or subtrat\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:24
384	8	383 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:24
385	6	S84 and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:43
386	5	\$34 and descriptor adj (defect or fault or flaw)	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/06 11:46

\$87	573639	(wafer\$1 or semicondudor\$1 or chip\$1 or subtrat\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:04
388	19	S87 and defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:05
389	640949	S88 and select\$3 and review and data file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:05
390	2	S98 and select\$3 and review and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:05
91	8	S87 and display adj thumbnails	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:07
992	2	991 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:07
93	0	S92 and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:15
394	8	991 and parameters	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:27
395	1	S94 and automatic adj defect and recognition and(detect\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:29

S96	2	992 and display adj thumbnalis	US-PGPUB; USPAT; EPO; UPO; DERWENT; 1BM_TDB	OR	ON	2008/12/17 19:30
397	2	596 and parameters	US-PGPUB; USPAT; EPO; JPO; DEFWENT; IBM_TDB	OR	ON	2008/12/17 19:30
398	0	997 and circuits	US-PGPUB; USPAT; EPO; UPO; DEFWENT; IBM_TDB	OR	ON	2008/12/17 19:31
399	0	597 and defect and (classification or classifier or classify)	US-PGPUB; USPAT; EPO; UPO; DEFWENT; IBM_TDB	OR	ON	2008/12/17 19:32
\$100	0	997 and(dassification or dassifier or dassify or grouping)	US-PGPUB; USPAT; EPO; JPO; DEFWENT; IBM_TDB	OR	ON	2008/12/17 19:33
3101	0	997 and intensity	US-PGPUB; USPAT; EPO; JPO; DEFWENT; IBM_TDB	OR	ON	2008/12/17 19:33
3102	2	997 and (intensity or contrast or brightness)	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:34
3103	2	S102 and (illumination or source or light)	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:34
S104	2	S103 and(blank adj wafer\$1 or wafer\$1)	US-PGPUB; USPAT; EPO; UPO; DEFWENT; IBM_TDB	OR	ON	2008/12/17 19:36

S105	2	S104 and(polymer or layer or oxide adj layer or contact or metal)	US-PGPUB; USPAT; EPO; UPO; DERWENT; BM_TDB	OR	ON	2008/12/17 19:38
106	0	S105 and lens	US-RGPUB; USPAT; EPO; UPO; DERWENT; BM_TDB	OR	ON	2008/12/17 19:39
107	0	S105 and focus	US-RGPUB; USPAT; EPO; UPO; DERWENT; BM_TDB	OR	ON	2008/12/17 19:39
108	0	S105 and magnificati\$3	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:40
109	2	S105 and @ad< "20030712"	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:40
110	2	S109 and select\$3 adj recipe	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/17 19:41
111	2	"6973209".pn.	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:40
112	0	Stitl and alignment	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:40
5113	1	S111 and align\$3	US-PGPUB; USPAT; EPO; UPO; DEFWENT; IBM_TDB	OR	ON	2008/12/19 15:40

S114	0	S111 and align\$3 same light	US-PGPUB; USPAT; EPO; UPO; DEFWENT; IBM_TDB	OR	ON	2008/12/19 15:41
3115	1	S111 and align\$3 and(light or source or illuminat\$3)	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:41
3116	1	S115 and adjusting	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:42
S117	0	S116 and optimal adj intensity	US-PGPUB; USPAT; EPO; UPO; DEFWENT; IBM_TDB	OR	ON	2008/12/19 15:42
3118	1	S116 and optimal	US-POPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:42
3119	0	S118 and intensity	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:42
3120	1	S118 and parameters	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:43
5121	1	S120 and algorithm	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:46
5122	1	S121 and automatic	US-PGPUB; USPAT; EPO; UPO; DERWENT; UBM_TDB	OR	ON	2008/12/19 15:47

S123	0	S122 and intensity	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:47
5124	1	S122 and (intensity or contrast or brightness)	US PGPUB; USPAT; EPO; UPO; DERWENT; BM_TDB	OR	ON	2008/12/19 15:47
S125	0	S124 and text adj image\$1	US-PGPUB; USPAT; EPO; UPO; DERWENT; BM_TDB	OR	ON	2008/12/19 15:48
S126	0	S124 and text	US-PGPUB; USPAT; EPO; UPO; DERWENT; BM_TDB	OR	ON	2008/12/19 15:48
3127	1	S124 and recipe	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:49
S128	0	S127 and review	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:49
5129	1	S127 and dictionary	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:49
S130	1	S129 and registered	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 15:50
S131	1	S130 and drag	US-PGPUB; USPAT; EPO; UPO; DEFIWENT; (BM_TDB	OR	ON	2008/12/19 15:51

S132	82	defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:09
3133	18	\$132 and select\$3 and review and data adj file	US-PGPUB; US-PAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:09
3134	16	S133 and @ad< "20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:09
3135	0	S132 and select\$3 same review adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:13
3136	5	S132 and review adj data	US PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:13
3137	3	S136 and @ad<"20030712"	US PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:14
3138	1	S137 and descriptors	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:19
\$139	0	S137 and defect adj descriptors	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/19 16:20
S140	82	defect and classification and knowledge adj database	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:44

S141	5	S140 and review adj data	US-PGPUB; US-PAT; EPO; JPO; DEFWENT; IBM_TDB	OR	ON	2008/12/30 11:44
3142	3	S141 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:44
S143	2	S142 and(wafer\$1 or semicondudor\$1 or chip\$1 or subtrat\$1)	US-PGPUB; US-PAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:45
3144	3	"6408219".pn.	US-PGPUB; USPAT; EPO; JPO; DEFWENT; IBM_TDB	OR	ON	2008/12/30 11:46
3145	1	S144 and review adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:47
3146	1	S144 and select\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:48
5147	732	select\$3 same review adj data	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:50
5148	62	S147 and(wafer\$1 or semicondudor\$1 or chip\$1 or subtrat\$1)	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:50
5149	0	S148 and defect and classification and knowledge adj database	US-PGPUB; US-PAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:50

S150	0	S148 and classification and knowledge adj database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:50
S151	14	S148 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:51
S152	0	S151 and display adj thumbnails	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:51
S153	0	S151 and display and thumbnails	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:52
S154	0	S151 and thumbnails	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 11:52
S155	0	S151 and automatic and defect adj recognition	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 12:12
S156	0	S151 and select\$3 adj recipe	US-PGPUB; USPAT; EPO; JPO; DEFWENT; IBM_TDB	OR	ON	2008/12/30 12:13
S157	1	S151 and align\$3 and(light or source or illuminat\$3)	US-PGPUB; USPAT; EPO; JPO; DEFWENT; IBM_TDB	OR	ON	2008/12/30 12:13
S158	0	S157 and(user or operator or human) and page and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 12:16

S159	0	S157 and descriptors	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 12:16
\$160	0	S157 and parameters	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 12:36
S161	11	automatic adj defect and recognition and(defect\$3 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3)and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 15:58
3162	5	S161 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 15:58
3163	1	S162 and learning adj mode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 15:58
3164	0	S163 and memory adj circuits	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 15:58
3165	575216	(wafer\$1 or semicondudor\$1 or chip\$1 or subtrat\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 15:58
3166	10	S165 and automatic adj defect and recognition and(defect33 or determining)and(defect or flaw or fault)and(assign\$3 or test\$3 or evaluat\$3)and descriptor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 15:59
S167	643423	S166 and select\$3 and review and data file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 15:59

S168	1	S166 and select\$3 and review and data adj file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:00
3169	0	S168 and @ad<"20030712"	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:00
\$170	1	S166 and memory adj circuits	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:00
S171	0	S170 and @ad<"20030712"	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:01
5172	4	S166 and @ad<"20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:01
3173	0	S172 and memory adj circuits	US-PGPUB; USPAT; EPO; UPO; DERWENT; I BM_TDB	OR	ON	2008/12/31 16:01
5174	7745	S165 and memory adj circuits	US-PGPUB; USPAT; EPO; UPO; DERWENT; I BM_TDB	OR	ON	2008/12/31 16:01
3175	2341	S174 and parameters	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:01
S176	775	S175 and logic adj circuits	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:02

S177	9	S176 and blank adj wafer	(US-PGPUB; (USPAT; EPO; UPO; (DERWENT; (IBM_TDB	OR	ON	2008/12/31 16:02
3178	8	S177 and @ad< "20030712"	US PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:03
179	0	S178 and resist	US PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:03
3180	0	S178 and photo adj resist	US PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:03
181	0	S178 and polymer adj layer	US-PGPUB; USPAT; EPO; UPO; DERWENT; !BM_TDB	OR	ON	2008/12/31 16:04
182	51765	polymer adj layer	US PGPUB; USPAT; EPO; UPO; DERWENT; !BM_TDB	OR	ON	2008/12/31 16:04
183	33269	S182 and @ad< "20030712"	US PGPUB; USPAT; EPO; UPO; DERWENT; !BM_TDB	OR	ON	2008/12/31 16:04
184	2388	S183 and oxide adj layer	US PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:05
3185	1703	S184 and contact	US PGPUB; USPAT; BPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:05

S186	16332	S183 and contact	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:05
S187	10	S186 and metal adj later	US PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:06
\$188	1	S187 and parameters	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:06
S189	1	S188 and @ad<*20030712*	US PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:06
3190	1	S189 and(intensity or contrast or brightness)	US POPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:07
3191	0	S190 and align\$3 and(light or source or illuminat\$3)	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:07
3192	1	S190 and(light or source or illuminat\$3)	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:07
3193	0	S192 and magnificat\$3	US-PGPUB; USPAT; EPO; UPO; DEFWENT; IBM_TDB	OR	ON	2008/12/31 16:08
S194	0	S192 and lens	US-PGPUB; USPAT; EPO; UPO; DERWENT; (BM_TDB	OR	ON	2008/12/31 16:08

S195	0	S192 and histogram	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:08
3196	0	S195 and focus\$3	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2008/12/31 16:12
3197	51832	polymer adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:04
3198	33269	S197 and @ad<"20030712"	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:04
3199	16332	S198 and contact	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:04
200	10	S199 and metal adj later	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:04
3201	1	©200 and parameters	(US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:04
5202	1	\$201 and @ad<"20030712"	(US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:04
S203	1	\$202 and(intensity or contrast or brightness)	(US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:04

\$204	1	\$203 and(light or source or illuminat\$3)	US PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:04
205	0	S204 and metal adj layer	(US-PGPUB; USPAT; EPO; UPO; DEF:WENT; IBM_TDB	OR	ON	2009/01/02 14:05
206	1	S204 and metal	US-PGPUB; USPAT; EPO; JPO; DEFWENT; IBM_TDB	OR	ON	2009/01/02 14:06
207	0	S206 and bright adj field	US-PGPUB; USPAT; BPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:07
208	0	S206 and bright	US PGPUB; USPAT; BPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:07
209	1	S206 and (UV or DUV)	US PGPUB; USPAT; EPO; JPO; DEFWENT; IBM_TDB	OR	ON	2009/01/02 14:08
210	0	S209 and lens	US PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:08
211	0	S209 and intensity	US PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:09
 3212	1	S209 and contrast	US PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:10

S213	0	S212 and histogram	US-PGPUB; USPAT; EPO; JPO; DEFWENT; IBM_TDB	OR	ON	2009/01/02 14:10
\$214	795256	select\$3 and review and data file	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:12
3215	2665	S214 and polymer adj layer	US-PGPUB; USPAT; BPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:13
\$216	12	S215 and bright adj field	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:13
217	9	\$216 and (UV or DUV)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:13
218	3	S217 and @ad< "20030712"	US-PGPUB; USPAT; EPO; JPO; DEFWENT; IBM_TDB	OR	ON	2009/01/02 14:13
 2219	3	S218 and intensity	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:13
3220 3220	0	S219 and histogram	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:14
5221	0	S219 and metal adj layer	US-PGPUB; USPAT; EPO; UPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:14

\$222	0	S219 and lens	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:14
\$223	4	S216 and lens	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:15
\$224	0	S223 and @ad< "20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:15
\$225	0	\$223 and @ad< "20030712"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/02 14:15

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